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The Global Market for Thermal Interface Materials 2023-2033

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Abstracts

The effective transfer/removal of heat from a semiconductor device is crucial to ensure reliable operation and to enhance the lifetime of these components. The development of high-power and high-frequency electronic devices has greatly increased issues with excessive heat accumulation. There is therefore a significant requirement for effective thermal management materials to remove excess heat from electronic devices to ambient environment.

Thermal interface materials (TIMs) offer efficient heat dissipation to maintain proper functions and lifetime for these devices. TIMs are materials that are applied between the interfaces of two components (typically a heat generating device such as microprocessors, photonic integrated circuits, etc. and a heat dissipating device e.g. heat sink) to enhance the thermal coupling between these devices. A range of Carbon-based, metal/solder and filler-based TIMs are available both commercially and in the research and development (R&D) phase.

Report contents include:

Analysis of recent commercial and R&D developments in thermal interface materials (TIMs).

Market trends and drivers.

Market map.

Analysis of thermal interface materials (TIMs) including:
Thermal Pads/Insulators.

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Thermally Conductive Adhesives.

Thermal Compounds or Greases.

Thermally Conductive Epoxy/Adhesives.

Phase Change Materials.

Metal-based TIMs.

Carbon-based TIMs.

Market analysis. Markets covered include:

Consumer electronics.

Electric Vehicles (EV) batteries.

Data Center infrastructure.

ADAS sensors.

EMI shielding.

5G.

Global market revenues for thermal interface materials (TIMs), segmented by type and market, historical and forecast to 2033.

Profiles of 87 producers. Companies profiled include Arieca, Carbice Corporation, CondAlign, Fujipoly, Henkel, Indium Corporation, KULR Technology Group, Inc., Parker-Hannifin Corporation, Shin-Etsu Chemical Co., Ltd, and SHT Smart High-Tech AB.

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